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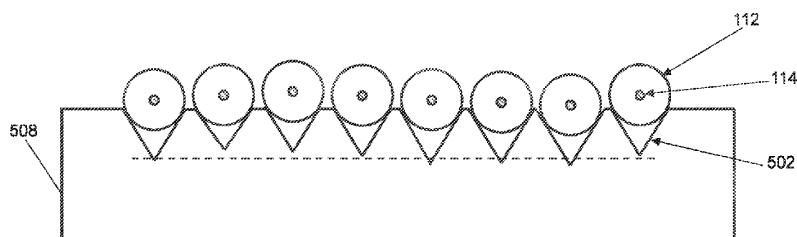
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(54) Title: METHODS AND DEVICES FOR EFFICIENT OPTICAL COUPLING BETWEEN OPTICAL FIBERS AND PHOTONIC INTEGRATED CHIPS



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FIG. 5B

(57) Abstract: Method and structures for edge coupling between waveguides of a photonic integrated circuit (PIC) chip with warpage and an optical fiber array. Some methods are used for measured displacements of waveguide facets due to PIC chip warpage. Some methods and structures are provided for fabricating the optical fiber array using the measured waveguide displacements to improve the optical coupling efficiency between the individual waveguides and optical fibers.

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